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- **Dual Output Voltages for Split-Supply Applications**
- 3.3-V/Adjustable Output, 3.3 V/1.8 V, and 3.3 V/2.5
- **Dropout Voltage < 80 mV Max at** $I_{O} = 100 \text{ mA } (3.3-\text{V option})$
- Low Quiescent Current, Independent of Load . . . 340 μA Typ Per Regulator
- Ultra-Low-Current Sleep State . . . 2 µA Max
- **Dual Active-Low Reset Signals with 200-ms Pulse Width**
- Output Current Range of 0 mA to 750 mA Per Regulator
- 28-Pin PowerPAD™ TSSOP Package

(TOP VIEW) NC □ □ 1RESET 27 NC \square \square NC 1GND □□ 26 ☐ NC 25 1EN 1FB/SENSE 1IN □ 5 24 10UT 23 П 6 **-** □ 10UT 1IN 22 NC \square 2RESET NC \square 21 8 2GND \Box 9 20 □ NC 19 2EN 🗆 10 □□ 2SENSE 2IN \Box 11 18 □□ 20UT 12 17 2IN \Box **Ⅲ** 20UT NC \square 13 16 \square NC NC \square 15 □ NC

PWP PACKAGE

NC - No internal connection

description

The TPS73HD3xx family of dual voltage regulators offers very low dropout voltages and dual outputs in a compact package. Designed primarily for DSP applications, these devices can be used in any mixed-output voltage application with each regulator supporting up to 750 mA. Output current can be allocated as desired between the two regulators and used to power many of todays DSPs. Low guiescent current and very low dropout voltage assure maximum power usage in battery-powered applications. Texas Instruments PowerPAD TSSOP package allows use of these devices with any voltage/current combination within the range of the listed specifications without thermal problems, provided proper device mounting procedures are followed. Separate inputs allow the designer to configure the source power as desired. Dual active-low reset signals allow resetting of core-logic and I/O separately. Remote sense/feedback terminals provide regulation at the load. The TPS73HD3xx are available in 28-pin PowerPAD TSSOP. They operate over a free-air temperature range of –40°C to 125°C.

AVAILABLE OPTIONS

TA	REGULATOR 1 V _O (V)	REGULATOR 2 V _O (V)	TSSOP (PWP)
	Adj (1.2 – 9.75 V)	3.3 V	TPS73HD301PWPR
-40°C to 125°C	1.8 V	3.3 V	TPS73HD318PWPR
	2.5 V	3.3 V	TPS73HD325PWPR

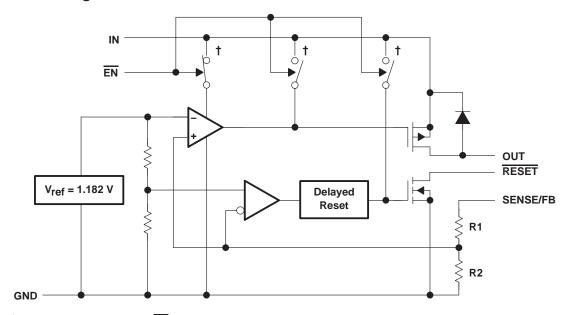


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PowerPAD is a trademark of Texas Instruments Incorporated



functional block diagram



† Switch positions shown with $\overline{\mathsf{EN}}$ low (active).

OUTPUT VOLTAGE	R1	R2	UNIT
Adjustable	0	∞	Ω
1.8 V	122	233	kΩ
2.5 V	260	233	kΩ
3.3 V	420	233	kΩ

Terminal Functions

TERM	INAL		
NAME	NO.	1/0	DESCRIPTION
NC	1, 2, 7, 8, 13–16, 20, 21, 26, 27		No connection
1GND	3		Regulator #1 ground
1EN	4	1	Regulator #1 enable, low = enable
1IN	5, 6	1	Regulator #1 input supply voltage
2GND	9		Regulator #2 ground
2EN	10	1	Regulator #2 enable, low = enable
2IN	11, 12	1	Regulator #2 input supply voltage
2OUT	17, 18	0	Regulator #2 output voltage
2SENSE	19	1	Regulator #2 output voltage sense (fixed output)
2RESET	22	0	Regulator #2 reset signal, low = reset
1OUT	23, 24	0	Regulator #1 output voltage
1FB/SENSE	25	I	Regulator #1 output voltage feedback (adjustable output)
1RESET	28	0	Regulator #1 reset signal, low = reset

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absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Input voltage range, V _I (xIN, xRESET, xSENSE, xEN)	0.3 V to 11 V
Differential input voltage, V _{ID} (1GND to 2GND)	2 V
Output current, I _O (10UT, 20UT)	2 A
Continuous total power dissipation	. See Dissipation Rating Tables
Operating free-air temperature range, T _A	40°C to 125°C
Storage temperature range, T _{Stq}	65°C to 150°C
Lead temperature soldering 1.6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltages are with respect to GND.

DISSIPATION RATING TABLE 1 - FREE-AIR TEMPERATURES\$

PACKAGE	AIR FLOW (CFM)	T _A < 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING
PWP‡	0	2.9 W	23.5 mW/°C	1.9 W	1.5 W
PWP+	300	4.3 W	34.6 mW/°C	2.8 W	2.2 W
PWP§	0	3 W	23.8 mW/°C	1.9 W	1.5 W
PMP3	300	7.2 W	57.9 mW/°C	4.6 W	3.8 W

[‡] This parameter is measured with the recommended copper heat sink pattern on a 1-layer PCB, 5-in × 5-in PCB, 1 oz. copper, 2-in × 2-in coverage (4 in²).

recommended operating conditions

		MII	I MAX	UNIT
Input voltage, VI [†]	Adjustable output (regulator #1)	2.9	7 10	V
Input voltage, V _I †	3.3-V output (regulator #2)	3.9	7 10	V
High-level input voltage	at EN, V _{IH}		2	V
Low-level input voltage a	at EN, V _{IL}		0.5	V
Total output current rang	e (per regulator), I _O		750	mA
Operating virtual junction	n temperature range, TJ	-4	125	°C

[†] Minimum input voltage defined in the recommended operating conditions is the maximum specified output voltage plus dropout voltage, V_{DO}, at the maximum specified load range (750 mA). Since dropout voltage is a function of output current, the usable range can be extended for lighter loads. To calculate the minimum input voltage for the maximum load current used in a given application, use the following equation:

$$V_{I(min)} = V_{O(max)} + V_{DO(max load)}$$

Because regulator 1 of the TPS373HD301 is programmable, $r_{DS(on)}$ should be used to calculate V_{DO} before applying the above equation. The equation for calculating V_{DO} from $r_{DS(on)}$ is given in Note 3 in the TPS73HD301 electrical characteristics table. The minimum value of 3.5 V is the absolute lower limit for the recommended input voltage range for the TPS73HD301. With 2.97-V input voltage, the LDO may be in dropout and will not meet the 3% regulator output or 750-mA load current specification.



[§] This parameter is measured with the recommended copper heat sink pattern on a 8-layer PCB, 1.5-in × 2-in PCB, 1 oz. copper with layers 1, 2, 4, 5, 7, and 8 at 5% coverage (0.9 in²) and layers 3 and 6 at 100% coverage (6 in²).

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electrical characteristics, V_{I(IN)} = 4.3 V, I_O = 10 mA, $\overline{\text{EN}}$ = 0 V, C_O = 4.7 $\mu\text{F/CSR}^{\ddagger}$ = 1 Ω , SENSE/FB shorted to OUT (unless otherwise noted)

	PARAMETER	TEST CONDITIONS§	TJ	MIN	TYP	MAX	UNIT
		<u>EN</u> ≤ 0.5 V,	25°C		340	415	
	Quiescent current (active mode), each regulator	0 mA \leq I _O \leq 750 mA, See NOTE 2	-40°C to 125°C			550	μΑ
1	Cumply augment (standby made) and regulator	$\overline{EN} = V_{I},$	25°C		0.01	0.5	
ICC	Supply current (standby mode), each regulator	NOTE 2	–40°C to 125°C			2	μΑ
1-	Output summent limit and has well atom	V- 0 V 40V	25°C	0.8	1.2	2	_
Ю	Output current limit, each regulator	$V_{O} = 0, V_{I} = 10 \text{ V}$	-40°C to 125°C			2	Α
	Dans also and lead are assessed (standless and a)	$\overline{EN} = V_{I},$	25°C		0.01	0.5	
l _{lkg}	Pass-element leakage current (standby mode)	See NOTE 2	-40°C to 125°C			1	μΑ
	Output voltage temperature coefficient		-40°C to 125°C		61	75	ppm/°C
	Thermal shutdown junction temperature				165		°C
	Lasta kink (FN) (standburga da)	$2.5 \text{ V} \le \text{V}_{\text{I}} \le 6 \text{ V},$	4000 1- 40500	2			.,
	Logic high (EN) (standby mode)	6 V ≤ V _I ≤ 10 V	-40°C to 125°C	2.7			V
	(-1) (; ;)	0 11075.0	25°C			0.5	.,
	Logic low (EN) (active mode)	See NOTE 2	-40°C to 125°C			0.5	V
V _{hys}	Hysteresis voltage (EN)		25°C		50		mV
		0.1/ .1/ .40.1/	25°C	-0.5	0.001	0.5	
II	Input current (EN)	0 V ≤ V _I ≤ 10 V	-40°C to 125°C	-0.5		0.5	μΑ
	Market Control of Control		25°C		2.05	2.5	.,
	Minimum input voltage, for active pass element		-40°C to 125°C			2.5	V
	Minimum involved to the Control of DECET		25°C		1	1.5	,,
	Minimum input voltage, for valid RESET	$IO(RESET) = -300 \mu A$	-40°C to 125°C			1.9	V

[‡] CSR (compensation series resistance) refers to the total series resistance, including the equivalent series resistance (ESR) of the capacitor, any series resistance added externally, and PWB trace resistance to C_O.

NOTE 2: Minimum input voltage is 3.5V or Vo(typ) + 1V whichever is greater.

The minimum value of 3.5 V is the absolute lower limit for the recommended input voltage range for the TPS73HD301.

[§] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

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electrical characteristics, $V_{I(IN)}$ = 4.3 V, I_O = 10 mA, \overline{EN} = 0 V, C_O = 4.7 μ F/CSR[†] = 1 Ω , SENSE/FB shorted to OUT (unless otherwise noted) (continued)

adjustable regulator

	PARAMETER	TEST CONDIT	TIONS‡	TJ	MIN	TYP	MAX	UNIT
	Defense velle ve (AFD)	$5 \text{ mA} \le I_{\text{O}} \le 750 \text{ mA},$		25°C		1.182		V
	Reference voltage (1FB)	See NOTE 2		-40°C to 125°C	1.147		1.217	V
	Reference voltage temperature coefficient			-40°C to 125°C		61	75	ppm/°C
		$50 \mu A \le I_0 \le 750 \text{ mA},$		25°C		0.52	1	
	Pass-element series resistance (see	See NOTE 2		-40°C to 125°C			1	
	Note 3)	$V_I = 3.9 \text{ V}, 50 \mu\text{A} \le$	I _O ≤ 750 mA	25°C		0.32		Ω
		$V_{I} = 5.9 \text{ V}, 50 \mu\text{A} \le$	I _O ≤ 750 mA	25°C		0.23		
	Input regulation	$V_I = 3.5 \text{ V}, 50 \mu\text{A} \leq 10^{-3} $	O ≤ 750 mA	25°C		3		mV
		I _O = 5 mA to 750 mA, See NOTE 2		25°C		7		mV
	Output regulation	$I_O = 50 \mu A \text{ to } 750 \text{ mA},$ See NOTE 2		25°C		10		mV
		f = 120 Hz,	I _O = 50 μA	25°C		59		
	Ripple rejection	f = 120 Hz,	I _O = 500 mA	25°C		54		dB
	Output noise-spectral density	f = 120 Hz		25°C		2		mV/√ Hz
			$C_L = 4.7 \mu F$	25°C		95		
	()utnut noise voltage	10 Hz \leq f \leq 100 kHz, CSR = 1 Ω	C _L = 10 μF	25°C		89		μV/rms
		OSK = 1 12	C _L = 100 μF	25°C		74		
V _(TO)	Trip-threshold voltage (RESET)§	V _{O(FB)} decreasing	_	-40°C to 125°C	1.101		1.145	V
V _{hys}	Hysteresis voltage (RESET)§	Measured at VO(ER)		25°C		12		mV
				25°C		0.1	0.4	
VOL	Low-level output voltage (RESET)§	$V_{I} = 2.13 \text{ V}, I_{O(RE)}$	SET) = 400 μA	-40°C to 125°C			0.4	V
				25°C	-10	0.1	10	
l _l	Input current (1FB)			-40°C to 125°C	-20		20	nA

[†] CSR (compensation series resistance) refers to the total series resistance, including the equivalent series resistance (ESR) of the capacitor, any series resistance added externally, and PWB trace resistance to C_I.

NOTE 3: To calculate dropout voltage, use equation:

$$V_{DO} = I_O \times r_{DS(ON)}$$

 $r_{DS(ON)}$ is a function of both output current and input voltage. This parametric table lists $r_{DS(ON)}$ for $V_I = 3.9$ V and 5.9 V, which corresponds to dropout conditions for programmed output voltages of 4 V and 6 V respectively. For other programmed values, refer to Figure 29.



[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

[§] Output voltage programmed to 2.5 V with closed-loop configuration (see application information)

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electrical characteristics, V_{I(IN)} = 4.3 V, I_O = 10 mA, $\overline{\text{EN}}$ = 0 V, C_O = 4.7 $\mu\text{F/CSR}^{\dagger}$ = 1 Ω , SENSE/FB shorted to OUT (unless otherwise noted) (continued)

1.8-V regulator (TPS73HD318)

	PARAMETER	TEST CON	NDITIONS‡	TJ	MIN	TYP	MAX	UNIT	
\/ -	Outrot valtage	427/27/2407/		25°C	1.746	1.8	1.854	V	
Vo	Output voltage	$4.3 \text{ V} \le \text{V}_{\text{I}} \le 10 \text{ V}$		-40°C to 125°C	1.728		1.872	V	
	Pass-element series	(3.5 V – V _O)/I _O .	V _I = 3.5 V,	25°C		0.5	1	0	
	resistance	I _O = 750 mA,	V _{2SENSE} = 0 V§	-40°C to 125°C			1.2	Ω	
	Input regulation	$50~\mu A \leq I_O \leq 750~mA,$	See NOTE 2	25°C		6		mV	
	Output as and offers	$I_0 = 5 \text{ mA to } 750 \text{ mA},$	See NOTE 2	25°C		14		\/	
	Output regulation	$I_O = 50 \mu A$ to 750 mA, See NOTE 2		25°C		18		mV	
	Dinale valenties	f = 120 Hz,	ΙΟ = 50 μΑ	25°C		51		5	
	Ripple rejection	f = 120 Hz,	I _O = 500 mA	25°C		49		dB	
	Output noise-spectral density	f = 120 Hz		25°C		2		mV/√Hz	
			C _L = 4.7 μF	25°C		274			
	Output noise voltage	10 Hz \leq f \leq 100 kHz, CSR = 1 Ω	C _L = 10 μF	25°C		228		μV/rms	
		33.1 = 1 12	C _L = 100 μF	25°C		159			

[†] CSR (compensation series resistance) refers to the total series resistance, including the equivalent series resistance (ESR) of the capacitor, any series resistance added externally, and PWB trace resistance to C_L.

[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

[§] Pass-element series resistance measured with sense pin disconnected from output to allow output voltge to rise to full saturation.

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electrical characteristics, $V_{I(IN)}$ = 4.3 V, I_O = 10 mA, \overline{EN} = 0 V, C_O = 4.7 $\mu F/CSR^{\dagger}$ = 1 Ω , SENSE/FB shorted to OUT (unless otherwise noted) (continued)

2.5-V regulator (TPS73HD325)

	PARAMETER	TEST CO	NDITIONS‡	TJ	MIN	TYP	MAX	UNIT
,,	Outrotudiana	407/47/407/		25°C	2.45	2.5	2.55	V
Vo	Output voltage	$4.3 \text{ V} \le \text{V}_{\text{I}} \le 10 \text{ V}$		-40°C to 125°C	2.425		2.575	V
	Dropout voltage	I _O = 750 mA,	V _I = 3.5 V	-40°C to 125°C			800	mV
	Input regulation	$50~\mu A \leq I_O \leq 750~mA,$	See NOTE 2	25°C		6		mV
	Outrast resolution	$I_0 = 5 \text{ mA to } 750 \text{ mA},$	See NOTE 2	25°C		20		mV
	Output regulation	$I_O = 50 \mu\text{A}$ to 750 mA	, See NOTE 2	25°C		25		mV
	B	f = 120 Hz,	I _O = 50 μA	25°C		51		15
	Ripple rejection	f = 120 Hz,	I _O = 500 mA	25°C		49		dB
	Output noise-spectral density	f = 120 Hz		25°C		2		mV/√ Hz
			C _L = 4.7 μF	25°C		274		
	Output noise voltage	10 Hz \leq f \leq 100 kHz, CSR = 1 Ω	C _L = 10 μF	25°C		228		μV/rms
		001(= 1 32	C _L = 100 μF	25°C		159		
V _(TO)	Trip-threshold voltage (RESET)	V _O decreasing		-40°C to 125°C	2.172			V
V _{hys}	Hysteresis voltage (RESET)			25°C		18		mV
,	Low-level output voltage	V 00V	1	25°C		0.17	0.4	.,
VOL	(RESET)	$V_{I} = 2.8 V,$	IO(RESET) = -1 mA	-40°C to 125°C			0.4	V

[†] CSR (compensation series resistance) refers to the total series resistance, including the equivalent series resistance (ESR) of the capacitor, any series resistance added externally, and PWB trace resistance to C_L.

switching characteristics

PARAMETER	TEST CONDITIONS	TJ	MIN	TYP	MAX	UNIT
The sect delay (DEOST)	05	25°C	140	200	260	
Time-out delay (RESET)	See Figure 3	-40°C to 125°C	100		300	ms

[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

[§] Pass-element series resistance measured with sense pin disconnected from output to allow output voltge to rise to full saturation.

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electrical characteristics, V_{I(IN)} = 4.3 V, I_O = 10 mA, $\overline{\text{EN}}$ = 0 V, C_O = 4.7 $\mu\text{F/CSR}^{\dagger}$ = 1 Ω , SENSE/FB shorted to OUT (unless otherwise noted) (continued)

3.3-V regulator (TPS73HD301)

	PARAMETER	TEST CON	NDITIONS‡	TJ	MIN	TYP	MAX	UNIT
\/ -	Outout valtage	401/21/2401/		25°C		3.3		V
VO	Output voltage	$4.3 \text{ V} \le \text{V}_{\text{I}} \le 10 \text{ V}$		-40°C to 125°C	3.23		3.37	V
		$I_O = 10 \text{ mA},$	V _I = 3.23 V	25°C		4.5	10	
	5	I _O = 100 mA,	V _I = 3.23 V	25°C		44	100	.,
	Dropout voltage			25°C		353	750	mV
		$I_O = 750 \text{ mA},$	$V_{I} = 3.23 \text{ V}$	-40°C to 125°C			800	
	Pass-element series	(3.23 V – V _O)/I _O ,	V _I = 3.23 V,	25°C		0.44	1	0
	resistance	I _O = 750 mA	•	-40°C to 125°C			1.07	Ω
	Input regulation	$50 \ \mu A \le I_O \le 750 \ mA$,	See NOTE 2	25°C		6		mV
	0.1.1.1.1	$I_0 = 5 \text{ mA to } 750 \text{ mA},$	See NOTE 2	25°C		30		mV
	Output regulation	$I_O = 50 \mu\text{A} \text{ to } 750 \text{mA},$	See NOTE 2	25°C		37		mV
	51 1 1 1	f = 120 Hz,	I _O = 50 μA	25°C		51		
	Ripple rejection	f = 120 Hz,	I _O = 500 mA	25°C		49		dB
	Output noise-spectral density	f = 120 Hz		25°C		2		mV/√Hz
			C _L = 4.7 μF	25°C		274		
	Output noise voltage	10 Hz \leq f \leq 100 kHz, CSR = 1 Ω	C _L = 10 μF	25°C		228		μV/rms
		CSR = 1 12	C _L = 100 μF	25°C		159		
V _(TO)	Trip-threshold voltage (RESET)	V _O decreasing		-40°C to 125°C	2.868			V
V _{hys}	Hysteresis voltage (RESET)			25°C		18		mV
	Low-level output voltage	.,		25°C		0.17	0.4	.,
VOL	(RESET)	$V_I = 2.8 V$,	IO(RESET) = -1 mA	-40°C to 125°C			0.4	V

[†] CSR (compensation series resistance) refers to the total series resistance, including the equivalent series resistance (ESR) of the capacitor, any series resistance added externally, and PWB trace resistance to C_L.

switching characteristics

PARAMETER	TEST CONDITIONS	TJ	MIN	TYP	MAX	UNIT
Tara ant dalay (DECET)	0	25°C	140	200	260	
Time-out delay (RESET)	See Figure 3	-40°C to 125°C	100		300	ms

[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

PARAMETER MEASUREMENT INFORMATION

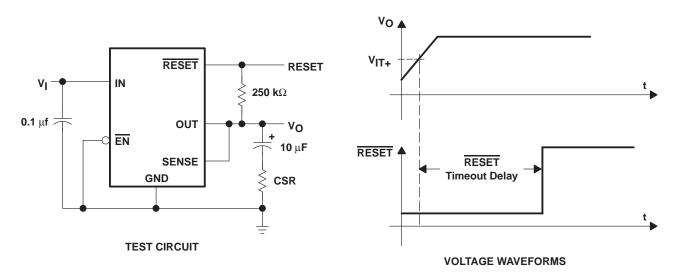


Figure 1. Test Circuit and Voltage Waveforms

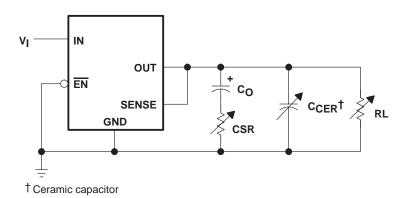


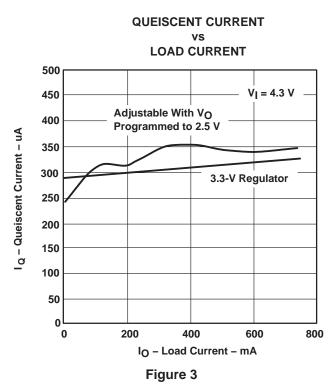
Figure 2. Test Circuit for Typical Regions of Stability (Refer to Figures 29 through 32)

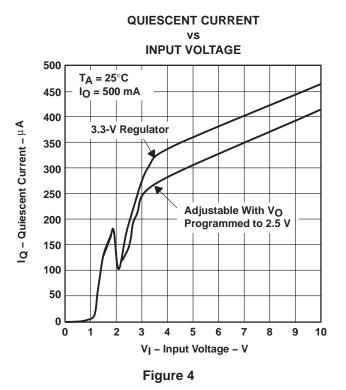
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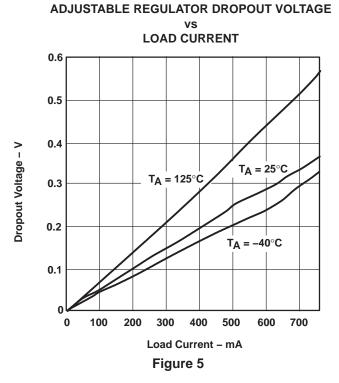
TYPICAL CHARACTERISTICS

Table of Graphs

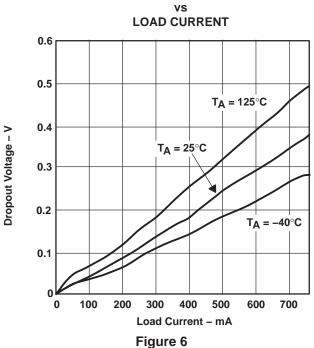
			vs Load current	5
IQ	Quiescent current		vs Input voltage	6
.,	B	Adjustable regulator	vs Load current	7
V_{DO}	Dropout voltage	3.3-V regulator	vs Load current	8
ΔV_{DO}	Change in dropout voltage		vs Free-air temperature	9
VDO	Dropout voltage		vs Output current	10
ΔVO	Change in output voltage		vs Free-air temperature	11
Vo	Output voltage		vs Input voltage	12
	Line regulation			13
Vo	Output voltage		vs Output current	14, 15
	Output voltage response from enable (EN)			16
	Load transient researce	Adjustable regulator		17
	Load transient response	3.3-V regulator		18
	Line transient response	Adjustable regulator		19
	3.3-V regulator			20
	Ripple rejection	vs Frequency	21	
	Output spectral noise density	vs Frequency	22	
			vs Output current	23
		Adjustable regulator	vs Added ceramic capacitance	24
	Compensation series resistance (CSR)		vs Output current	25
	Compensation series resistance (CSR)	3.3-V regulator	vs Output current	26
		Adjustable regulator	vs Added ceramic capacitance	27
		3.3-V regulator	vs Added ceramic capacitance	28
rDS(on)	Pass-element resistance		vs Input voltage	29
۷Į	Minimum input voltage for valid RESET		vs Free-air temperature	30
VIT−	Negative-going reset threshold		vs Free-air temperature	31
OL(RESET)	RESET output current	3.3-V regulato	vs Input voltage	32
^t d	Reset time delay		vs Free-air temperature	33
t _d	Distribution for reset delay		34	











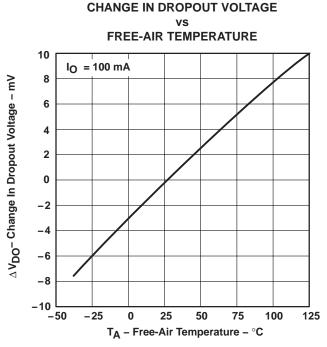
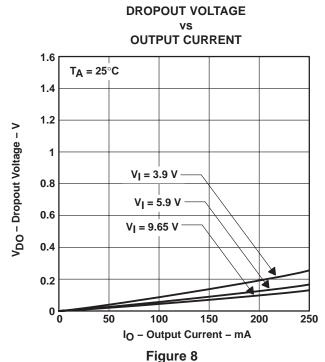
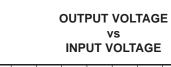
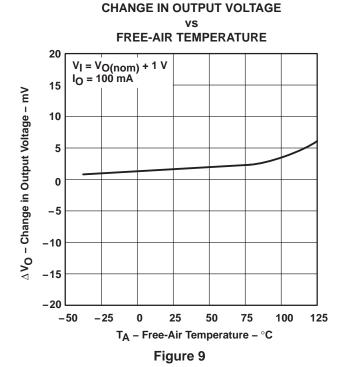


Figure 7







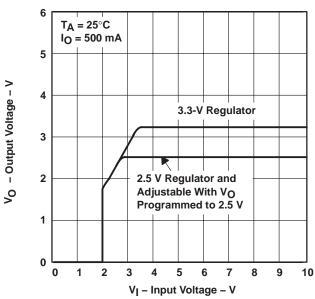
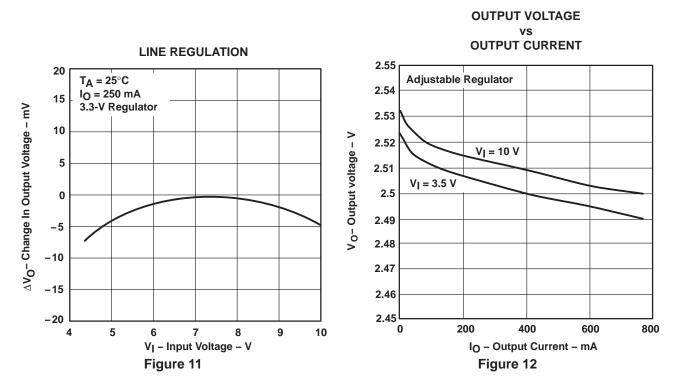


Figure 10



OUTPUT VOLTAGE vs OUTPUT CURRENT

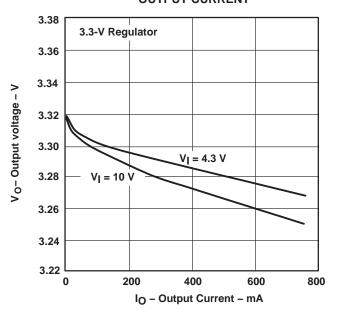


Figure 13

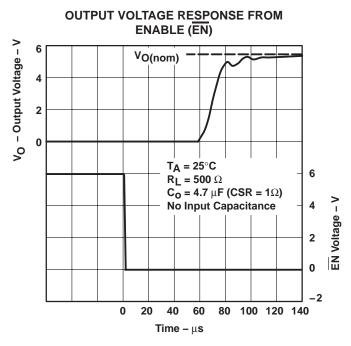
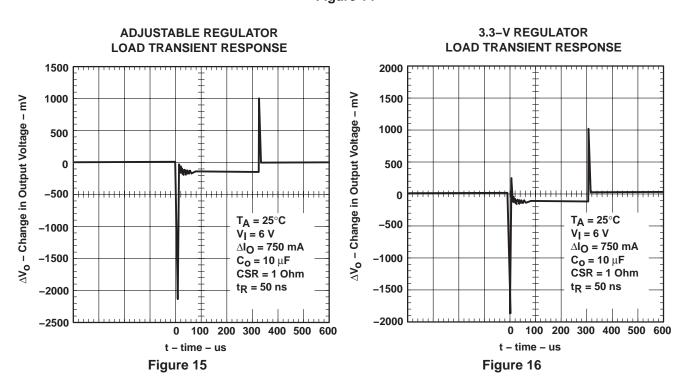


Figure 14



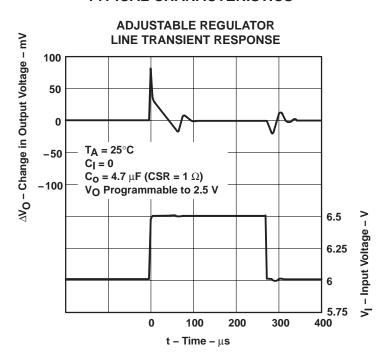


Figure 17

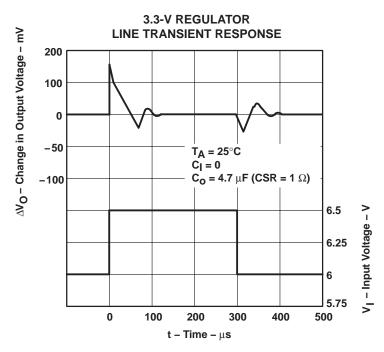


Figure 18

Output Spectral-Noise Density − μV/VHz

0.01

10

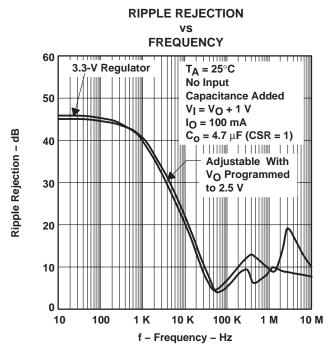
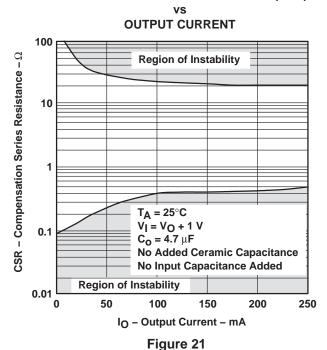


Figure 19

TYPICAL REGIONS OF STABILITY COMPENSATION SERIES RESISTANCE (CSR)[†]



TYPICAL REGIONS OF STABILITY COMPENSATION SERIES RESISTANCE (CSR)†

 $C_0 = 100 \,\mu\text{F} \,(\text{CSR} = 1 \,\Omega)$

100

vs

Figure 20

f - Frequency - Hz

OUTPUT SPECTRAL-NOISE DENSITY

FREQUENCY

T_A = 25°C

 $V_I = V_O + 1 V$

 $C_0 = 4.7 \,\mu\text{F} (CSR = 1 \,\Omega)$

No Input Capacitance Added

 $C_0 = 10 \mu F (CSR = 1 \Omega)$

10 k

100 k

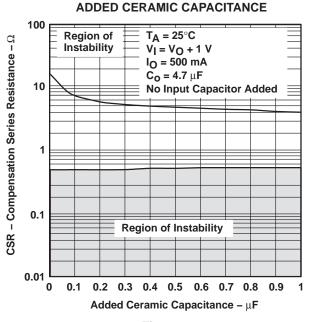
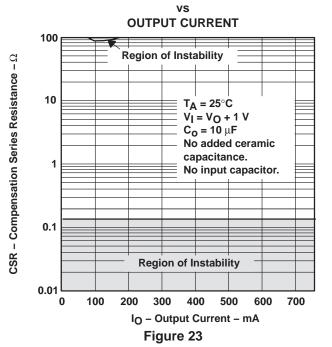


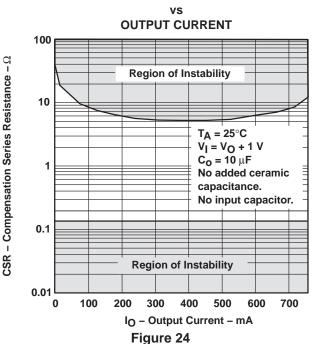
Figure 22



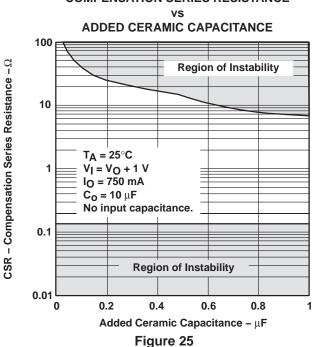
ADJUSTABLE REGULATOR TYPICAL REGIONS OF STABILITY COMPENSATION SERIES RESISTANCE



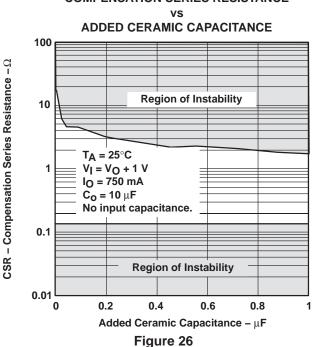
3.3-V REGULATOR TYPICAL REGIONS OF STABILITY COMPENSATION SERIES RESISTANCE

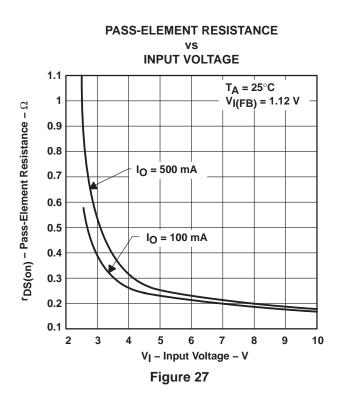


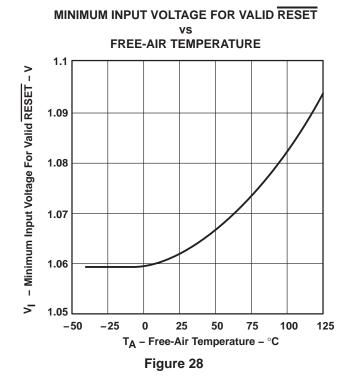
ADJUSTABLE REGULATOR TYPICAL REGIONS OF STABILITY COMPENSATION SERIES RESISTANCE

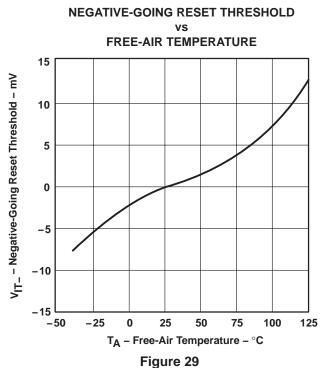


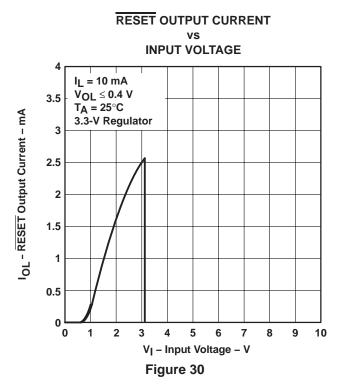
3.3-V REGULATOR TYPICAL REGIONS OF STABILITY COMPENSATION SERIES RESISTANCE

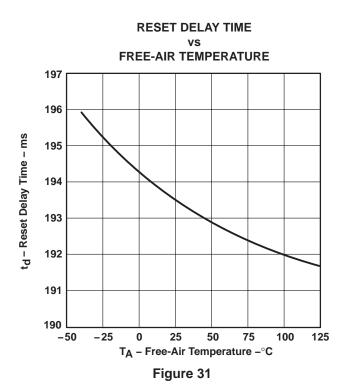


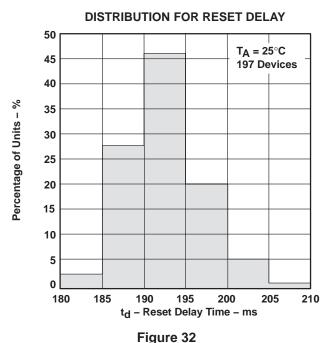












THERMAL INFORMATION

The TPS73HD3xx is packaged in a high-power dissipation downset lead frame for optimal power handling. with proper heat dissipation techniques, the full power soutput of these devices can be safely handled over the full temperture range. The Texas Instruments technical brief, *PowerPAD Thermally Enhanced Package* (literature number SLMA002), goes into considerable detail into techniques for properly mounting this type of package for maximum thermal performance. A thermal conduction plane of approximately 3" y 3" will give a power dissipatio level of 4.5 W.

Power dissipation within the device can be calculated with the following equation:

$$P_D = P_{IN} - P_{OUT} = V_I (I_{O1} + I_{O2}) - (V_{O1} \times I_{O1} + V_{O2} \times I_{O2})$$

APPLICATION INFORMATION

thermal considerations

DISSIPATION RATING TABLE

PACKAGE	AIR FLOW (CFM)	T _A < 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING
PWP [‡]	0	2.9 W	23.5 mW/°C	1.9 W	1.5 W
	300	4.3 W	34.6 mW/°C	2.8 W	2.2 W
55	0	3 W	23.8 mW/°C	1.9 W	1.5 W
PWP§	300	7.2 W	57.9 mW/°C	4.6 W	3.8 W

[†] This parameter is measured with the recommended copper heat sink pattern on a 1-layer PCB, 5-in \times 5-in PCB, 1 oz. copper, 2-in \times 2-in coverage (4 in²).

The maximum ambient temperature depends on the heatsinking ability of the PCB system. Using the 0 CFM and 300 CFM data from the dissipation rating table, the derating factor for the PWP package with 6.9 in² of copper area on a multilayer PCB is 24 mW/°C and 58 mW/°C respectively. Converting this to Θ_{JA} :

$$\Theta_{JA} = \frac{1}{Derating}$$

For 0 CFM: For 300 CFM:

$$= \frac{1}{0.0235} = \frac{1}{0.0579}$$

$$= 42.6^{\circ}\text{C/W}$$

$$= 17.3^{\circ}\text{C/W}$$

Given Θ_{JA} , the maximum allowable junction temperature, and the total internal dissipation, the maximum ambient temperature can be calculated with the following equation. The maximum recommended junction temperature for the TPS73HD3xx is 150 $^{\circ}$ C.

$$T_A Max = T_J Max - (\Theta_{JA} \times P_D)$$

The maximum power dissipation limit is determined using the following equation:

$$T_{D(max)} = \frac{T_{J} max - T_{A}}{R_{\theta,JA}}$$

Where:

T_Jmax is the maximum allowable junction temperature

 $R_{\theta JA}$ is the thermal resistance junction-to-free-air for the package (i.e., 285°C/W for the 5-terminal SOT-23 package.

TA is the free-air temperautre

The regulator dissipation is calculated using:

$$P_D = (V_I - V_O) \times 1_O$$

Power dissipation resulting from quiescent current is negligible.



[‡] This parameter is measured with the recommended copper heat sink pattern on an 8-layer PCB, 1.5-in × 2-in PCB, 1 oz. copper with layers 1, 2, 4, 5, 7, and 8 at 5% coverage (0.9 in²) and layers 3 and 6 at 100% coverage (6 in²).

APPLICATION INFORMATION

Capitalizing upon the features of the TPS73xx family (low-dropout voltage, low quiescent current, power-saving shutdown mode, and a supply-voltage supervisor) and the power-dissipation properties of the TSSOP PowerPAD package has enabled the integration of the TPS73HD3xx dual LDO regulator with high output current for use in DSP and other multiple voltage applications. Figure 35 shows a typical dual-voltage DSP application.

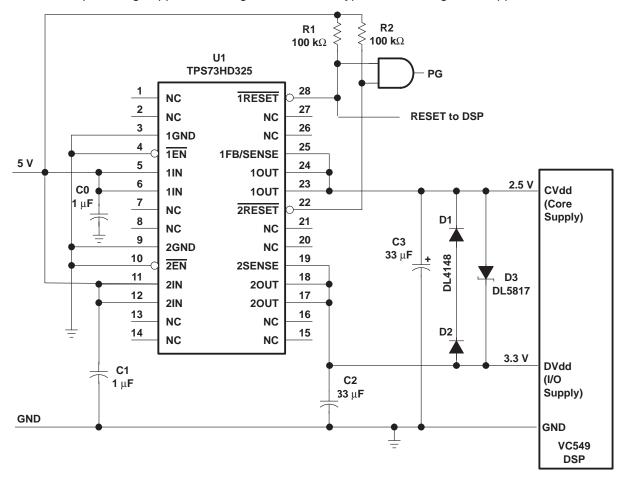


Figure 33. Dual-Voltage DSP Application

DSP power requirements include very high transient currents that must be considered in the initial design. This design uses higher-valued output capacitors to handle the large transient currents. Details of this type of design are shown in the application report, *Designing Power Supplies for TMS320VC549 DSP Systems*.

minimum load requirements

The TPS73HD3xx is stable even at zero load; no minimum load is required for operation.

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APPLICATION INFORMATION

SENSE connection

The SENSE terminal of fixed-output devices must be connected to the regulator output for proper functioning of the regulator. Normally, this connection should be as short as possible; however, the connection can be made near a critical circuit (remote sense) to improve performance at that point. Internally, SENSE connects to a high-impedance wide-bandwidth amplifier through a resistor-divider network, and noise pickup feeds through to the regulator output. It is essential to route the SENSE connection in such a way as to minimize/avoid noise pickup. Adding an RC network between SENSE and OUT to filter noise is not recommended because it can cause the regulator to oscillate.

external capacitor requirements

An input capacitor is not required; however, a ceramic bypass capacitor (0.047 pF to 0.1 μ F) improves load transient response and noise rejection when the TPS73HD3xx is located more than a few inches from the power supply. A higher-capacitance electrolytic capacitor may be necessary if large (hundreds of milliamps) load transients with fast rise times are anticipated.

As with most LDO regulators, the TPS73HD3xx requires an output capacitor for stability. A low-ESR 10- μ F solid-tantalum capacitor connected from the regulator output to ground is sufficient to ensure stability over the full load range (see Figure 44). Adding high-frequency ceramic or film capacitors (such as power-supply bypass capacitors for digital or analog ICs) can cause the regulator to become unstable unless the ESR of the tantalum capacitor is less than 1.2 Ω over temperature. Capacitors with published ESR specifications such as the AVX TPSD106M035R0300 and the Sprague 593D106X0035D2W work well because the maximum ESR at 25°C is 300 m Ω (typically, the ESR in solid-tantalum capacitors increases by a factor of 2 or less when the temperature drops from 25°C to -40°C). Where component height and/or mounting area is a problem, physically smaller, 10- μ F devices can be screened for ESR. Figures 23 through 28 show the stable regions of operation using different values of output capacitance with various values of ceramic load capacitance.

Due to the reduced stability range available when using output capacitors smaller than 10 μ F, capacitors in this range are not recommended. Larger capacitors provide a wider range of stability and better load transient response. Because capacitor minimum ESR is seldom if ever specified, it may be necessary to add a 0.5- Ω to 1- Ω resistor in series with the capacitor and limit ESR to 1.5 Ω maximum. As shown in the CSR graphs (Figures 23 through 28), minimum ESR is not a problem when using 10- μ F or larger output capacitors.

Below is a partial listing of surface-mount capacitors usable with the TPS73HD3xx. This information, along with the CSR graphs, is included to assist in selection of suitable capacitance for the user's application. When necessary to achieve low height requirements along with high output current and/or high ceramic load capacitance, several higher ESR capacitors can be used in parallel to meet the guidelines above.



APPLICATION INFORMATION

external capacitor requirements (continued)

All load and temperature conditions with up to 1 µF of added ceramic load capacitance:

PART NO.	MFR.	VALUE	MAX ESR†	SIZE $(H \times L \times W)^{\dagger}$
T421C226M010AS	Kemet	$22~\mu F,10~V$	0.5	$2.8\times 6\times 3.2$
593D156X0025D2W	Sprague	15 μF, 25 V	0.3	$2.8\times7.3\times4.3$
593D106X0035D2W	Sprague	10 μF, 35 V	0.3	$2.8\times7.3\times4.3$
TPSD106M035R0300	AVX	10 μF, 35 V	0.3	$2.8 \times 7.3 \times 4.3$

Load < 200 mA, ceramic load capacitance < 0.2 μF, full temperature range:

PART NO.	MFR.	VALUE	MAX ESR†	SIZE $(H \times L \times W)^{\dagger}$
592D156X0020R2T	Sprague	15 μF, 20 V	1.1	$1.2\times7.2\times6$
595D156X0025C2T	Sprague	15 μ F, 25 V	1	$2.5\times7.1\times3.2$
595D106X0025C2T	Sprague	10 μF, 25 V	1.2	$2.5\times7.1\times3.2$
293D226X0016D2W	Sprague	$22 \mu F$, $16 V$	1.1	$2.8\times7.3\times4.3$

Load < 100 mA, ceramic load capacitance < 0.2 μ F, full temperature range:

PART NO.	MFR.	VALUE	MAX ESR†	SIZE $(H \times L \times W)^{\dagger}$
195D106X06R3V2T	Sprague	10 μ F, 6.3 V	1.5	$1.3\times3.5\times2.7$
195D106X0016X2T	Sprague	10 μ F, 16 V	1.5	$1.3\times7\times2.7$
595D156X0016B2T	Sprague	15 μF, 16 V	1.8	$1.6\times3.8\times2.6$
695D226X0015F2T	Sprague	$22~\mu\text{F},15~\text{V}$	1.4	$1.8\times6.5\times3.4$
695D156X0020F2T	Sprague	15 μ F, 20 V	1.5	$1.8\times6.5\times3.4$
695D106X0035G2T	Sprague	10 μF, 35 V	1.3	$2.5 \times 7.6 \times 2.5$

 $[\]dagger$ Size is in mm. ESR is maximum resistance at 100 kHz and T_A = 25°C. Listings are sorted by height.

APPLICATION INFORMATION

programming the adjustable LDO regulator output

Programming the adjustable regulator is done using an external resistor divider as shown in Figure 44. The equation governing the output voltage is:

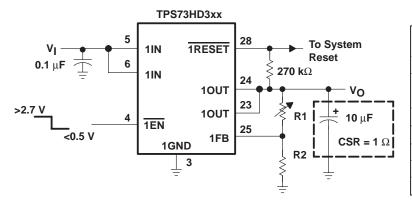
$$V_O = V_{ref} \times \left(1 + \frac{R1}{R2}\right)$$

Where

V_{ref} = reference voltage, 1.182 V typ

Resistors R1 and R2 should be chosen for approximately 7- μ A divider current. A recommended value for R2 is 169 k Ω with R1 adjusted for the desired output voltage. Smaller resistors can be used, but offer no inherent advantage and consume more power. Larger values of R1 and R2 should be avoided as leakage currents at FB will introduce an error. Solving for R1 yields a more useful equation for choosing the appropriate resistance:

$$R1 = \left(\frac{V_0}{V_{ref}} - 1\right) \times R2$$



OUTPUT VOLTAGE PROGRAMMING GUIDE

OUTPUT VOLTAGE	RESET VOLTAGE	R1	R2	UNIT
1.5 V	-†	45.3	169	kΩ
1.8 V	-†	88.7	169	kΩ
2.5 V	2.37 V	191	169	kΩ
3.3 V	3.13 V	309	169	kΩ
3.6 V	3.42 V	348	169	kΩ
4 V	3.80 V	402	169	kΩ
5 V	4.75 V	549	169	kΩ
6.4 V	6.08 V	750	169	kΩ

† Non-operational below 1.9 V

Figure 34. TPS7301 Adjustable LDO Regulator Programming

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APPLICATION INFORMATION

undervoltage supervisor function

The RESET outputs of the TPS73HD3xx initiate a reset in microcomputer and microprocessor systems in the event of an undervoltage condition. An internal comparator in the TPS73HD3xx monitors the output voltage of the regulator to detect the undervoltage condition. When that occurs, the RESET output transistor turns on, taking the RESET signal low.

At programmed output voltages below 1.9 V (on the adjustable regulator only) and on the 1.8 V regulator the reset function becomes unusable. With a minimum output voltage requirement for a valid RESET signal (over temperature) being 1.9 V, RESET will not operate reliably in this range.

On power up, the output voltage tracks the input voltage. The $\overline{\text{RESET}}$ output becomes active (low) as V_I approaches the minimum required for a valid $\overline{\text{RESET}}$ signal (specified at 1.5 V for 25°C and 1.9 V over full recommended operating temperature range). When the output voltage reaches the appropriate positive-going input threshold (V_{IT+}), a 200-ms (typical) timeout period begins during which the $\overline{\text{RESET}}$ output remains low. Once the timeout has expired, the $\overline{\text{RESET}}$ output becomes inactive. Since the $\overline{\text{RESET}}$ output is an open-drain NMOS, a pullup resistor should be used to ensure that a logic-high signal is indicated.

The supply-voltage-supervisor function is also activated during power down. As the input voltage decays and after the dropout voltage is reached, the output voltage tracks linearly with the decaying input voltage. When the output voltage drops below the specified negative-going input threshold (V_{IT-} — see electrical characteristics tables), the \overline{RESET} output becomes active (low). It is important to note that if the input voltage decays below the minimum required for a valid \overline{RESET} , the \overline{RESET} is undefined.

Since the circuit is monitoring the regulator output voltage, the RESET output can also be triggered by disabling the regulator or by any fault condition that causes the output to drop below V_{IT} . Examples of fault conditions include a short circuit on the output and a low input voltage. Once the output voltage is reestablished, either by reenabling the regulator or removing the fault condition, then the internal timer is initiated, which holds the $\overline{\text{RESET}}$ signal active during the 200-ms (typical) timeout period.

Transient loads or line pulses can also cause a reset to occur if proper care is not taken in selecting the input and output capacitors. Load transients that are faster than 5 μ s can cause a reset if high-ESR output capacitors (greater than approximately 7 Ω) are used. A 1- μ s transient causes a reset when using an output capacitor with greater than 3.5 Ω of ESR. Note that the output-voltage spike during the transient can drop well below the reset threshold and still not trip if the transient duration is short. A 1- μ s transient must drop at least 500 mV below the threshold before tripping the reset circuit. A 2- μ s transient trips RESET at just 400 mV below the threshold. Lower-ESR output capacitors help by reducing the drop in output voltage during a transient and should be used when fast transients are expected.

NOTE: $V_{IT+} = V_{IT-} + Hysteresis$

output noise

The TPS73HD3xx has very low output noise, with a spectral noise density < $2 \,\mu V/\sqrt{Hz}$. This is important when noise-susceptible systems, such as audio amplifiers, are powered by the regulator.

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APPLICATION INFORMATION

regulator protection

The TPS73HD3xx PMOS-pass transistors have built-in back diodes that safely conduct reverse currents when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. If extended reverse voltage is anticipated, external limiting might be appropriate.

The TPS73HD3xx also features internal current limiting and thermal protection. During normal operation, the TPS73HD3xx limits output current to approximately 1 A. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds 165°C, thermal-protection circuitry shuts it down. Once the device has cooled, regulator operation resumes.



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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
TPS73HD301PWP	Active	Production	HTSSOP (PWP) 28	50 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	PS73HD301
TPS73HD301PWP.A	Active	Production	HTSSOP (PWP) 28	50 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	PS73HD301
TPS73HD301PWP.B	Active	Production	HTSSOP (PWP) 28	50 TUBE	-	Call TI	Call TI	-40 to 125	
TPS73HD301PWPR	Active	Production	HTSSOP (PWP) 28	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	PS73HD301
TPS73HD301PWPR.A	Active	Production	HTSSOP (PWP) 28	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	PS73HD301
TPS73HD301PWPR.B	Active	Production	HTSSOP (PWP) 28	2000 LARGE T&R	-	Call TI	Call TI	-40 to 125	
TPS73HD318PWP	Active	Production	HTSSOP (PWP) 28	50 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	PS73HD318
TPS73HD318PWP.A	Active	Production	HTSSOP (PWP) 28	50 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	PS73HD318
TPS73HD318PWP.B	Active	Production	HTSSOP (PWP) 28	50 TUBE	-	Call TI	Call TI	-40 to 125	
TPS73HD318PWPR	Active	Production	HTSSOP (PWP) 28	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	PS73HD318
TPS73HD318PWPR.A	Active	Production	HTSSOP (PWP) 28	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	PS73HD318
TPS73HD318PWPR.B	Active	Production	HTSSOP (PWP) 28	2000 LARGE T&R	-	Call TI	Call TI	-40 to 125	
TPS73HD325PWP	Active	Production	HTSSOP (PWP) 28	50 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	PS73HD325
TPS73HD325PWP.A	Active	Production	HTSSOP (PWP) 28	50 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	PS73HD325
TPS73HD325PWP.B	Active	Production	HTSSOP (PWP) 28	50 TUBE	-	Call TI	Call TI	-40 to 125	
TPS73HD325PWPG4	Active	Production	HTSSOP (PWP) 28	50 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	PS73HD325
TPS73HD325PWPR	Active	Production	HTSSOP (PWP) 28	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	PS73HD325
TPS73HD325PWPR.A	Active	Production	HTSSOP (PWP) 28	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	PS73HD325
TPS73HD325PWPR.B	Active	Production	HTSSOP (PWP) 28	2000 LARGE T&R	-	Call TI	Call TI	-40 to 125	

⁽¹⁾ Status: For more details on status, see our product life cycle.

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

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(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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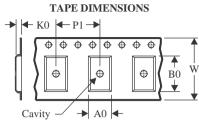
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

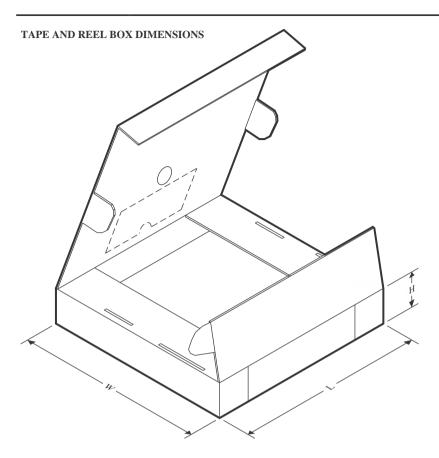
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS73HD301PWPR	HTSSOP	PWP	28	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1
TPS73HD318PWPR	HTSSOP	PWP	28	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1
TPS73HD325PWPR	HTSSOP	PWP	28	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1

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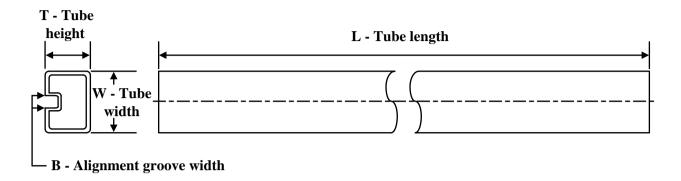
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS73HD301PWPR	HTSSOP	PWP	28	2000	350.0	350.0	43.0
TPS73HD318PWPR	HTSSOP	PWP	28	2000	350.0	350.0	43.0
TPS73HD325PWPR	HTSSOP	PWP	28	2000	350.0	350.0	43.0

PACKAGE MATERIALS INFORMATION

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TUBE



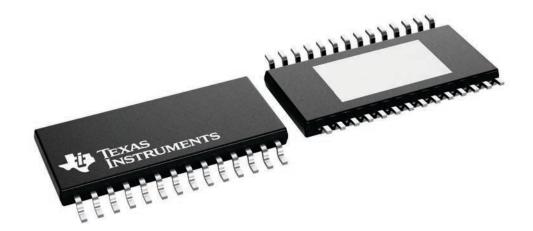
*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
TPS73HD301PWP	PWP	HTSSOP	28	50	530	10.2	3600	3.5
TPS73HD301PWP.A	PWP	HTSSOP	28	50	530	10.2	3600	3.5
TPS73HD318PWP	PWP	HTSSOP	28	50	530	10.2	3600	3.5
TPS73HD318PWP.A	PWP	HTSSOP	28	50	530	10.2	3600	3.5
TPS73HD325PWP	PWP	HTSSOP	28	50	530	10.2	3600	3.5
TPS73HD325PWP.A	PWP	HTSSOP	28	50	530	10.2	3600	3.5
TPS73HD325PWPG4	PWP	HTSSOP	28	50	530	10.2	3600	3.5

4.4 x 9.7, 0.65 mm pitch

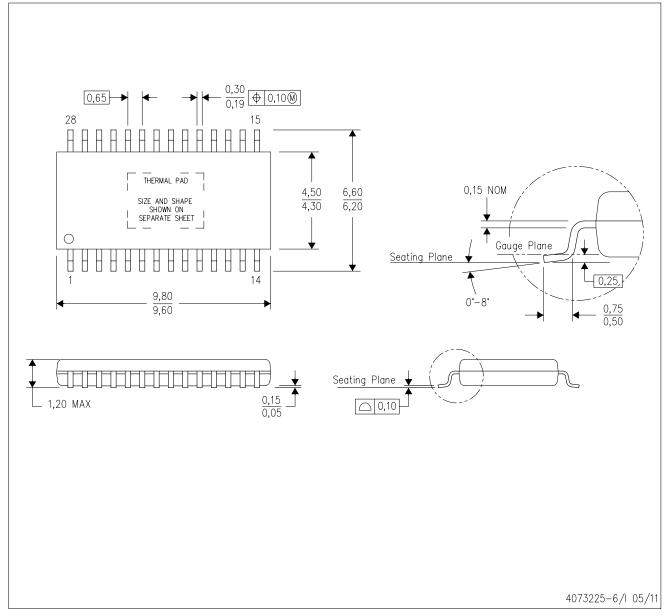
SMALL OUTLINE PACKAGE

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



PWP (R-PDSO-G28)

PowerPAD™ PLASTIC SMALL OUTLINE



NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusions. Mold flash and protrusion shall not exceed 0.15 per side.
- This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com www.ti.com.

 E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- E. Falls within JEDEC MO-153

PowerPAD is a trademark of Texas Instruments.



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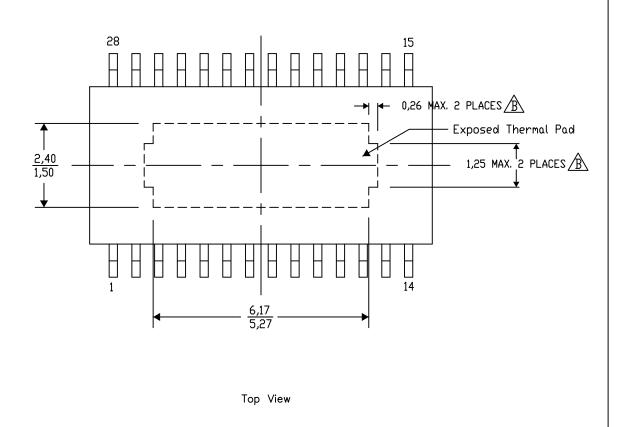
PWP (R-PDSO-G28) PowerPAD™ SMALL PLASTIC OUTLINE

THERMAL INFORMATION

This PowerPADTM package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



NOTE: A. All linear dimensions are in millimeters

B. Exposed tie strap features may not be present.

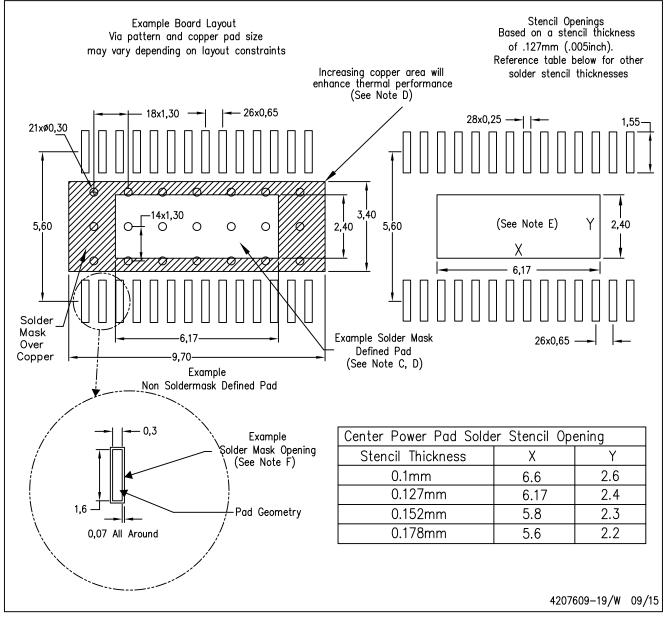
PowerPAD is a trademark of Texas Instruments



Exposed Thermal Pad Dimensions

PWP (R-PDSO-G28)

PowerPAD™ PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets.
- E. For specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com www.ti.com. Publication IPC-7351 is recommended for alternate designs. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil
- F. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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